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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	. ATTORNEY DOCKET NO.	CONFIRMATION NO
10/657,140	09/09/2003	Hong-Mi Park	SEC.1042	1912
20987 75	590 09/29/2004		EXAMINER	
VOLENTINE FRANCOS, & WHITT PLLC			YEVSIKOV, VICTOR V	
ONE FREEDOM SQUARE 11951 FREEDOM DRIVE SUITE 1260		ART UNIT	PAPER NUMBER	
RESTON, VA	20190		2825	
			DATE MAILED: 09/29/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
Office Action Commence	10/657,140	PARK ET AL.			
Office Action Summary	Examiner	Art Unit			
	Victor Yevsikov	2825			
The MAILING DATE of this communication apperiod for Reply	opears on the cover sheet with the	correspondence address			
A SHORTENED STATUTORY PERIOD FOR REPI THE MAILING DATE OF THIS COMMUNICATION  - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a re  - If NO period for reply is specified above, the maximum statutory period  - Failure to reply within the set or extended period for reply will, by statu Any reply received by the Office later than three months after the mailine earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply be ti ply within the statutory minimum of thirty (30) da d will apply and will expire SIX (6) MONTHS fron te, cause the application to become ABANDONE	mely filed ys will be considered timely. n the mailing date of this communication. ED (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on	14/04				
	· is action is non-final.				
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the practice under	•				
Disposition of Claims					
4) Claim(s) 1-14 is/are pending in the applicatio	n				
4a) Of the above claim(s) is/are withdrawn from consideration.					
5) Claim(s) is/are allowed.					
6)⊠ Claim(s) <u>1-14</u> is/are rejected.	•	•			
7) Claim(s) is/are objected to.					
8) Claim(s) are subject to restriction and/	or election requirement.				
Application Papers		,			
9) The specification is objected to by the Examin	ner.				
10) ☐ The drawing(s) filed on is/are: a) ☐ ac		Examiner.			
Applicant may not request that any objection to the					
Replacement drawing sheet(s) including the corre	ction is required if the drawing(s) is ob	ojected to. See 37 CFR 1.121(d).			
11) The oath or declaration is objected to by the E	Examiner. Note the attached Office	e Action or form PTO-152.			
Priority under 35 U.S.C. § 119					
12)⊠ Acknowledgment is made of a claim for foreig	n priority under 25 U.S.C. \$ 110/a	) (d) or (f)			
a) ⊠ All b) ☐ Some * c) ☐ None of:	in phonty under 35 0.5.C. § 119(a	i)-(d) or (i).			
1.⊠ Certified copies of the priority documents have been received.					
2. Certified copies of the priority documer		ion No.			
3. Copies of the certified copies of the pri					
application from the International Burea					
* See the attached detailed Office action for a lis	t of the certified copies not receive	ed.			
044 m m la una a mat ( a )		•			
Attachment(s)  Notice of References Cited (PTO-892)	A) T Interview Summer	(PTO 413)			
2) Notice of Draftsperson's Patent Drawing Review (PTO-948)	4) Interview Summary (PTO-413) Paper No(s)/Mail Date				
B) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date 7/14/04.	5) Notice of Informal F 6) Other:	Patent Application (PTO-152)			

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#### **DETAILED ACTION**

## Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1, 4-7, 9 and 14 are rejected under 35 U.S.C. 102(b) as being anticipated by Kim et al. (US 5,985,759).

With respect to claims 1, 4-7, 9 and 14 Kim teaches a method of forming a contact in a semiconductor device, comprising:

forming an insulating layer 14 on a semiconductor substrate 12;

forming a contact hole 18 in the insulating layer by selectively etching a potion of the insulating layer;

forming a barrier metal layer 16 and 20 having a uniform thickness on the insulating layer and a surface of the contact hole;

forming a wetting layer 26 of an oxidation-resistive metal material on the barrier metal layer, and

forming a metal layer 28 on the wetting layer so as to fill the contact hole, and wherein:

4. the wetting layer is formed at a temperature of about 18°C to about 600°C (table 1);

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- 5. the wetting layer is formed to a thickness of about 0-500Å;
- 6. the wetting layer is formed to such a thickness that sufficient space remains in the contact hole for the metal layer;
- 7. the barrier metal layer includes a titanium layer, a titanium nitride layer or a composite layer thereof;
- 9. the barrier metal layer is formed to such a thickness that sufficient space remains in the contact hole for the wetting layer and the metal layer;
- 14. the metal layer includes aluminum or an aluminum alloy.

Reference: figs. 1-7 with corresponding text.

# Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 2 and 3 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kim in view of Smith et al. (US 6,344,281 B1).

Kim teaches the features detailed previously but lacks a discussion of the method wherein the wetting layer of an oxidation-resistive metal material includes tungsten and wherein the wetting layer is formed by a chemical vapor deposition (CVD) process.

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However, Smith teaches the method wherein the wetting layer of the oxidation-resistive metal material includes tungsten and wherein the wetting layer is formed by a chemical vapor deposition (CVD) process (col. 3, lines 33-38).

Therefore, it would have been obvious to one of ordinary skill in the art to use tungsten for wetting layer and CVD for depositing it as taught by Kim/Smith as a means to reduce thickness.

Claim 8 is rejected under 35 U.S.C. 103(a) as being unpatentable over Kim ('759).

Kim ('759) teaches the features detailed previously but lacks a discussion of using the PVD method for depositing titanium or titanium nitride barrier layer.

However, the used PVD to form barrier layers is notoriously well known to one of ordinary skill in the art. To support this assertion examiner cites col. 1, lines 34-46 of Kim ('759).

Therefore, it would have been obvious to one of ordinary skill in the art to use PVD method for depositing titanium or titanium nitride barrier layer as taught by Kim ('759) for reduce stress and providing high bottom coverage.

Claims 10-13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kim ('759) in view of Kim et al. (US 2002/0098682 A1).

Kim ("759) teaches the features detailed previously but lacks a discussion of the method:

wherein the metal layer is formed by depositing a metal material to such a thickness that the contact hole is partially filled, and re-flowing the deposited metal

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material to completely fill the contact hole and the metal material is deposited through a chemical vapor deposition (CVD) process or a physical vapor deposition (PVD) process; and

wherein the metal layer is formed by depositing a first metal material on the wetting layer by a chemical vapor deposition (CVD) process to such a thickness that the contact hole is partially filled with the first metal material; depositing a second metal material on the first metal material by a physical vapor deposition (PVD) process, and re-flowing the first metal material and the second metal material to completely fill the contact hole and wherein the first metal material is the same as the second metal material.

However, Kim('682) teaches the method:

wherein the metal layer is formed by depositing a metal material to such a thickness that the contact hole is partially filled, and re-flowing the deposited metal material to completely fill the contact hole and the metal material is deposited through a chemical vapor deposition (CVD) process or a physical vapor deposition (PVD) process; and

wherein the metal layer is formed by depositing a first metal material on the wetting layer by a chemical vapor deposition (CVD) process to such a thickness that the contact hole is partially filled with the first metal material; depositing a second metal material on the first metal material by a physical vapor deposition (PVD) process, and re-flowing the first metal material and the second metal material to completely fill the

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contact hole and wherein the first metal material is the same as the second metal material.

Reference: §0038, claim 1.

Therefore, it would have been obvious to one of ordinary skill in the art to use PVD and CVD for depositing metal materials on the wetting layer as taught by Kim '759)/Kim (682) with results in controlling abnormal growth of the CVD metal.

#### Remarks

## Response to Arguments

Applicant's arguments with respect to claims 1-14 have been considered but they are not persuasive. The combinations detail each and every element of applicant's claims or further show the invention of applicant's is an obvious development from the prior art and using barrier layers.

Kim ('795) teach "...forming a wetting layer of a barrier metal", wherein the barrier layer is selected from the group consisting of Ti, Ta and W (col. 9, lines 1-5). In the claim 2 applicant teach "... the oxidation-resistive material includes tungsten". So, according the applicant, W is a oxidation resistant material and forming on a barrier metal layer (col. 8, lines 60-61).

### **Conclusion**

# Notice of Finality

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, THIS ACTION IS MADE FINAL. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1. 136(a).

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A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1. 136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Victor Yevsikov whose telephone number is (571) 272-1910. The examiner can normally be reached on Monday –Thursdays 8:00-5:30.

If attempts to reach the examiner by telephone are unsuccessful, examiner's supervisor, Matthew S. Smith, can be reached on (571) 272-1907. The fax phone numbers for the organization where this application or processing is assigned is (703) .

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published application may be obtained from either Private PAIR or Public PAIR. Status information for unpublished application is available through Private PAIR only. For more information about the PAIR system, see <a href="http://pair-direct.uspto.gov">http://pair-direct.uspto.gov</a>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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Victor Yevsikov Examiner Art Unit 2825

September 28, 2004

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SUPERVISORY PATENT EXAMINER
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